

TECHNICAL DATASHEET

SUPERMICRO · MULTI-NODE & TWIN

Supermicro 1 OU FlexTwin Server SYS-122FT-DEO-LCC

1 OU 2-Node FlexTwin with liquid cooling (complete rack and onsite service are required)

SKU SYS-122FT-DEO-LCC

LGA7529

Supermicro



FORM FACTOR

—

MAX POWER (BASE)

565 W

HEAT OUTPUT

1,928 BTU/h

PRICE

On request



CONFIGURE & QUOTE ONLINE

serverinvest.com/product/sys-122ft-deo-lcc

01 Product overview

The Supermicro SYS-122FT-DEO-LCC is a 1 OU FlexTwin Server built on dual Intel Xeon 6 processors with up to 6 TB of memory in 24 DIMM slots.

1 OU 2-Node FlexTwin with liquid cooling (complete rack and onsite service are required).

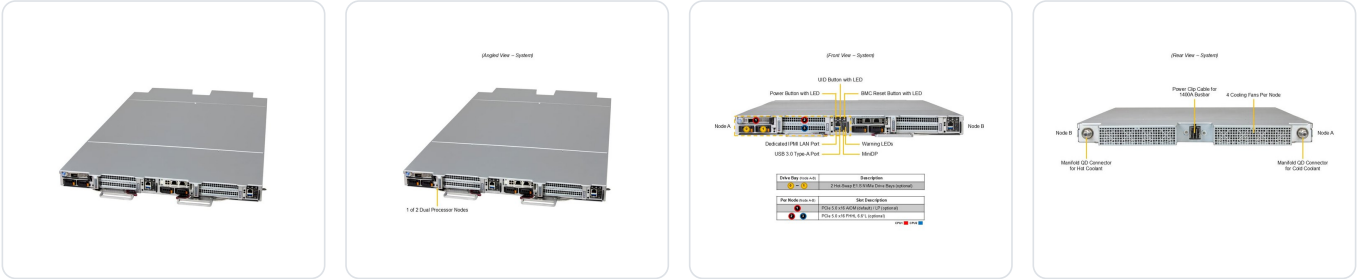
ServerInvest configures every SYS-122FT-DEO-LCC to order, updates BIOS and BMC firmware, installs your operating system on request and runs a 48-hour burn-in test before delivery. Every system includes a 3-year warranty.

KEY SPECIFICATIONS

Processor	2× Intel Xeon 6
Socket	LGA7529
Memory	24 DIMM slots, up to 6 TB
Memory type	DDR5-6400 ECC RDIMM
Drive bays	2 (2 NVMe)
Typical power draw	750 W
Networking	Via AIOM

HIGHLIGHTS

- Dual Intel Xeon 6
- Up to 6 TB memory · 24 DIMM slots
- Total 2 bays 2 front hot-swap E1.S PCIe 5.0 x4 NVMe* drive bays
- Networking: Via AIOM



02 Base configuration

Components included in the listed base price — every part can be changed in the online configurator

COMPONENT	DESCRIPTION	QTY
Base system	Supermicro 1 OU FlexTwin Server SYS-122FT-DEO-LCC	1
Processor	Intel Xeon 6710E Processor 64 Cores (96M Cache, 2.40Ghz) 205W	2
Memory	16GB 6400MT/s DDR5 ECC Registered DIMM Module	4
Warranty & support	3-year return-to-base warranty (included)	1

Price on request — contact us for a tailored quotation

03 Power & thermal

Calculated for the base configuration

IDLE	TYPICAL	MAXIMUM	HEAT (MAX)	COOLING	PSU LOAD
119 W	367 W	565 W	1,928 BTU/h	0.6 kW	—

Typical 367 W · max 565 W

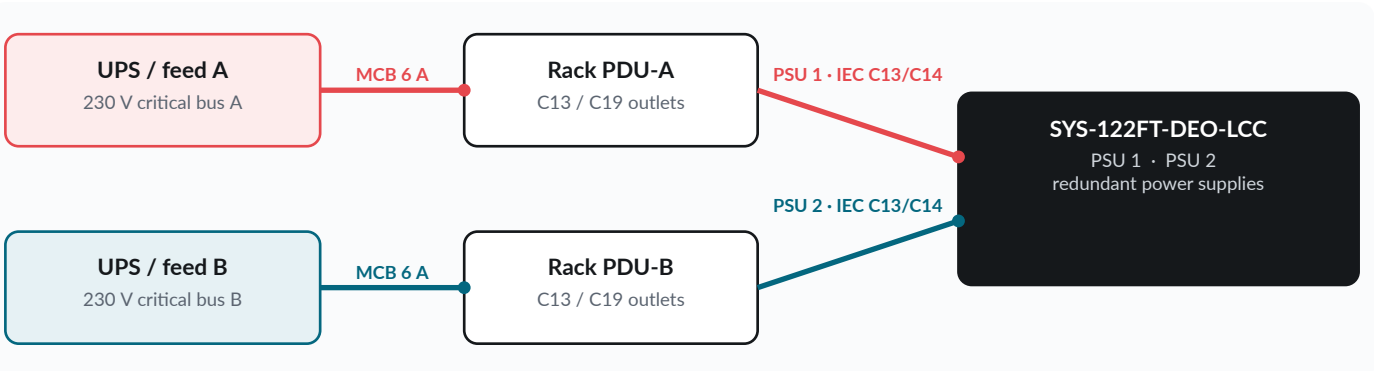
Annual IT energy (24/7)	2,563 kWh
Annual facility energy (PUE 1.5)	3,845 kWh
Annual energy cost	€513 IT · €769 incl. cooling (at 0.20 €/kWh)
CO ₂ emissions / year	1.00 t (grid factor 0.26 kg/kWh)
Power supplies	Redundant hot-swap PSUs — rating depends on the final configuration

POWER BY COMPONENT	IDLE	TYPICAL	MAX
Chassis, motherboard, fans, BMC	38 W	59 W	85 W
2× CPU — Intel Xeon 6710E Processor 64 Cores	62 W	266 W	410 W
4× Memory 16 GB DIMM	12 W	20 W	36 W

DC loads converted to wall power at 94% PSU efficiency; typical load assumed 70% of the time. Engineering estimates — confirm with the manufacturer's power calculator for critical designs.

04 Power connection diagram

Dual-feed (A/B) connection for redundant power supplies



- Connect PSU 1 to PDU-A and PSU 2 to PDU-B (independent feeds) using IEC C13/C14 power cords.
- Maximum current per feed: 2.6 A at 230 V — each feed must be able to carry the full load if the other fails.
- Recommended protection per PDU circuit: MCB 6 A, curve C; RCD according to local regulations.
- Heat to remove at full load: 565 W = 1,928 BTU/h (0.6 kW).

05 Full specifications

MOTHERBOARD

Super X14DBT-FLAP2

PROCESSOR (PER NODE)

CPU

Dual Socket BR (LGA-7529)
Intel Xeon 6900 Series processors with P-cores and Intel Xeon 6+ processors

Core Count	P-cores: Up to 128C/256T; Up to 504MB Cache per CPU E-cores: Up to 288C/288T; Up to 576MB Cache per CPU
Note	Supports up to 500W TDP CPUs (Liquid Cooled)

SYSTEM MEMORY (PER NODE)

Memory	Slot Count: 24 DIMM slots Max Memory (1DPC): Up to 3TB 8800MT/s ECC DDR5 MRDIMM (P-core only) Max Memory (1DPC): Up to 6TB 6400MT/s ECC DDR5 RDIMM (P-core) Max Memory (1DPC): Up to 3TB 8000MT/s ECC DDR5 RDIMM (E-core) View Memory Options
Memory Voltage	1.1V

ON-BOARD DEVICES (PER NODE)

NVMe	NVMe; RAID 0/1/5/10 support(Intel VROC RAID key required) View NVMe Options
Network Connectivity	Via AIOM View AIOM Options View AOC Options

INPUT / OUTPUT (PER NODE)

LAN	1 RJ45 1 GbE Dedicated BMC LAN port (ASPEED AST2600)
USB	1 USB 3.0 Type-A port (Front)
Video	1 Mini-DP port (Front)

SYSTEM BIOS

BIOS Type	AMI 64MB SPI Flash
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MANAGEMENT

Software	SuperCloud Composer (SCC) Supermicro Server Manager (SSM) Super Diagnostics Offline (SDO) Supermicro Thin-Agent Service (TAS) SuperServer Automation Assistant (SAA) New!
Power configurations	Power-on mode for AC power recovery ACPI Power Management

SECURITY

Hardware	Trusted Platform Module (TPM) 2.0 Silicon Root of Trust (RoT) – NIST 800-193 Compliant
Features	Cryptographically Signed Firmware Secure Boot Secure Firmware Updates Automatic Firmware Recovery Supply Chain Security: Remote Attestation Runtime BMC Protections System Lockdown

PC HEALTH MONITORING

CPU	Monitors for CPU Cores, Chipset Voltages, Memory
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Fan	Fans with tachometer monitoring Pulse Width Modulated (PWM) fan connectors Status monitor for speed control
Temperature	Monitoring for CPU and chassis environment

CERTIFICATIONS

Operating Systems	RHEL 10.0 View all OS Compatibility and Certification Matrix
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CHASSIS

Form Factor	1 OU Rackmount
Model	CSE-OC101TS-V01DFP

DIMENSIONS AND WEIGHT

Height	1.89" (48 mm)
Width	21.14" (537 mm)
Depth	33.66" (855 mm)
Package	7.17" (H) x 26.38" (W) x 44.29" (D)
Weight	Gross Weight: 89 lbs (40.37 kg) Net Weight: 58.5 lbs (26.54 kg)
Available Color	Silver

FRONT PANEL

Buttons	Power On/Off UID button
LED	Power status UID

EXPANSION SLOTS (PER NODE)

PCI-Express (PCIe) Configuration	Default* 1 PCIe 5.0 x16 (in x16) AIOM slot (OCP 3.0 compatible) Option A* 2 PCIe 5.0 x16 (in x16) FHHL slots 1 PCIe 5.0 x16 (in x16) LP slot (*Requires additional parts, please see the optional parts list for details. For more details on PCIe slot configuration options, please refer to the system callout images above.) View AOC Options
M.2	2 M.2 PCIe 5.0 x4 NVMe slots (M-key 22110(default); Optional Configuration)

DRIVE BAYS / STORAGE (PER NODE)

Drive Bays Configuration	Option A: Total 2 bays 2 front hot-swap E1.S PCIe 5.0 x4 NVMe* drive bays (*NVMe support may require additional storage controller and/or cables, please see the optional parts list for details) View NVMe Options
M.2	2 M.2 PCIe 5.0 x4 NVMe slots (M-key 22110(default); optional configuration)

SYSTEM COOLING

Fans	Up to 8 Fan 40mm Fan(s)
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Air Shroud	1 Air Shroud
Liquid Cooling	Direct to Chip (D2C) Cold Plate

OPERATING ENVIRONMENT

RoHS	RoHS Compliant
Environmental Spec.	Operating Temperature: 10°C to 35°C (50°F to 95°F) Non-operating Temperature: -30°C to 60°C (-22°F to 140°F) Operating Relative Humidity: 8% to 80% (non-condensing) Non-operating Relative Humidity: 8% to 90% (non-condensing)

06 Built, tested & supported by ServerInvest

Engineered configuration

Every option validated for socket, memory channels, PCIe lanes, power and cooling.

48-hour burn-in

Assembled, firmware-updated and stress-tested before it leaves our workshop.

3-year warranty

Standard on every system, with on-site next-business-day upgrades available.

Rack-ready delivery

Rails, cable management and labelling included — delivered across Europe.



Ready to order or need changes?

Configure this system online or talk to a solutions engineer — we reply within one business day.

office@serverinvest.com

Official manufacturer datasheet: serverinvest.com/product/sys-122ft-deo-lcc/datasheet/manufacture

